CLAIM AMENDMENTS

Please amend claims 1, 3, 4, 14, 15, 17 and 18 and add new claim 21 as follows:

1. (Currently Amended) A temperature compensation method for a physical property sensor, said method comprising the steps of:

locating a bridge circuit on a physical property sensor substrate wherein said bridge circuit comprises a plurality of components, including at least one heating element and a plurality of resistors, including at least one a plurality of compensating resistors—wherein said plurality of compensating resistors includes a temperature independent resistor for compensating a temperature coefficient of resistance of said at least one heating element—and—a temperature coefficient of resistance of said plurality of components and a temperature dependence—of—a physical property thereof;

simultaneously driving an imbalance of said bridge circuit to a zero value and a supply voltage thereof to a level required to stabilize said heating element at a required temperature rise above an ambient temperature, wherein said heating element comprises a thin-film heating material, ; and

adjusting the resistance value of said temperature independent resistor to compensate said temperature coefficient of resistance of said heating element(s): and

dynamically compensating for a temperature coefficient of resistance of said

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thin-film heating material and said a temperature dependence of said plurality of

components resistors and said heating element(s) of said bridge circuit components

and said a temperature dependence of a physical property thereof, utilizing said at

least one plurality of compensating resistors of said bridge circuit.

2. (Original) The method of claim 1 further comprising the step of configuring said

bridge circuit to comprise a Wheatstone Bridge circuit.

3. (Currently Amended) The method of claim1 further comprising the step of

modifying said bridge circuit such that said plurality of compensating resistors

includesto comprise at least one other temperature independent compensating

resistor, and

adjusting the value of said other temperature independent compensating

resistor such that, for said adjusted resistance value of said temperature

independent resistor, said heating element is maintained at said required

temperature rise above said ambient temperature.

4. (Currently Amended) The method of claim 1 further comprising the step of

increasing a resistance value of said at least one temperature independent

eompensating resistor to compensate for a temperature dependence of a physical

property value.

5. (Original) The method of claim 4, wherein said physical property value comprises

a value of at least one of the following: thermal conductivity, specific heat,

compressibility, octane number, heating value, speed of sound, and viscosity.

6. (Original) The method of claim 1 further comprising the steps of:

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measuring a heater power of said heating element at an approximately

constant temperature rise above said ambient temperature, wherein said

approximately constant temperature rise varies with said ambient temperature to

compensate for a combined effect of said thin-film heating material, said

components of said bridge circuit, and a fluid property to be measured by said

physical property sensor.

7. (Currently Amended) The method of claim 1 further comprising the step of

minimizing a change in a bridge voltage of said bridge circuit as said ambient

temperature is varied over a required range by an optimal choice of a value of said

temperature independent-compensating resistor.

8. (Original) The method of claim 7 further comprising the step of selecting said

bridge voltage as a supply voltage generated by an amplification of a bridge circuit

imbalance, such that said bridge voltage serves as a sensor output signal of said

physical property sensor.

9. (Cancelled)

10. (Original) The method of claim 1 wherein said bridge circuit comprises a front-

end analog circuit of said physical property sensor.

11. (Original) The method of claim 1 wherein said physical property sensor

comprises a gas property sensor.

12. (Original) The method of claim 1 wherein said physical property sensor

comprises a liquid property sensor.

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13. (Original) The method of claim 1 wherein said physical property sensor

comprises a solid property sensor.

14. (Currently Amended) A temperature compensation method for a physical

property sensor, said method comprising the steps of:

locating a bridge circuit on a physical property sensor substrate wherein said

bridge circuit comprises a plurality of components, including at least one heating

element and a plurality of resistors, including at least one a plurality of

compensating resistors, wherein said plurality of compensating resistors includes

first and second temperature independent resistors;

simultaneously driving an imbalance of said bridge circuit to a zero value and

a supply voltage thereof to a level required to stabilize said heating element at a

required temperature rise above an ambient temperature, wherein said heating

element comprises a thin-film heating material;

dynamically compensating for a temperature coefficient of resistance of said

thin-film heating material and a temperature dependence of said plurality of

components of resistors and said heating element(s) of said bridge circuit

components and a temperature dependence of a physical property thereof, utilizing

said at least one compensating resistors of said bridge circuit, wherein said physical

property includes at least one of the following: thermal conductivity, specific heat,

compressibility, octane number, heating value, speed of sound, and viscosity;

increasing a resistance value of said at least one first temperature

independent compensating resistor to compensate for a temperature dependence of

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a physical property value, wherein said physical property value comprises a value of at least one of the following: thermal conductivity, specific heat, compressibility, octane number, heating value, speed of sound, and viscosity;

adjusting the resistance value of said second temperature independent resistor such that, for said increased resistance value of said first temperature independent resistor, said heating element is maintained at said required temperature rise above said ambient temperature:

minimizing a change in a bridge voltage of said bridge circuit as said ambient temperature is varied over a required range by an optimal choice of a value of said <u>first temperature independent compensating</u> resistor; and

selecting said bridge voltage as a supply voltage generated by an amplification of a bridge circuit imbalance, such that said bridge voltage serves as a sensor output signal of said physical property sensor.

15. (Currently Amended) A temperature compensation system for a physical property sensor, comprising:

a bridge circuit comprising a plurality of components, including at least one heating element comprising a thin-film heating material and a plurality of resistors, including at least one a plurality of compensating resistors—wherein said plurality of compensating resistors includes a temperature independent resistor, the resistance value of said temperature independent resistor being adjusted to compensate for a temperature coefficient of resistance of said at least one heating element;

a physical property sensor substrate wherein said bridge circuit is located on

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said physical property sensor substrate and wherein an imbalance of said bridge

circuit is driven to a zero value while a supply voltage thereof is simultaneously

driven to a level required to stabilize said heating element at a required

temperature rise above an ambient temperature; and

a compensator for dynamically compensating for at a temperature coefficient

of resistance of said thin-film heating material and a temperature dependence of

said plurality of components <u>said resistors and said heating element(s)</u> of said

bridge circuit components and a temperature dependence of a physical property

thereof, wherein said compensator comprises said at least one plurality of

compensating resistors of said bridge circuit.

16. (Original) The system of claim 15 wherein said bridge circuit comprises a front-

end analog circuit of said physical property sensor and wherein said bridge circuit

further comprises a Wheatstone Bridge circuit.

17. (Currently Amended) The system of claim 15 wherein said plurality of

compensating resistors include bridge elreuit to comprise at least one other

temperature independent compensating resistor, the resistance value of said other

temperature independent resistor being adjusted such that, for said adjusted

resistance value of said temperature independent resistor, said heating element is

maintained at said required temperature rise above said ambient temperature.

18. (Currently Amended) The system of claim 15 wherein a resistance value of said

at least one temperature independent compensating resistor is increased to

compensate for a temperature dependence of a physical property value.

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- 19. (Original) The system of claim 18, wherein said physical property value comprises a value of at least one of the following: thermal conductivity, specific heat, compressibility, octane number, heating value, speed of sound, and viscosity.
- 20. (Original) The system of claim 15 wherein a heater power of said heating element is measurable at an approximately constant temperature rise above said ambient temperature, wherein said approximately constant temperature rise varies with said ambient temperature to compensate for a combined effect of said thin-film heating material, said components of said bridge circuit, and a fluid property to be measured by said physical property sensor.
- 21. (New) The system of claim 17 wherein said temperature independent resistor is arranged in series with a temperature dependent compensating resistor and wherein said other temperature independent resistor is arranged in parallel with said temperature dependent compensating resistor.

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